

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (Currently Amended)

A substrate treatment method comprising:

the droplet generating step of generating droplets of a treatment liquid by mixing the treatment liquid with a gas, the treatment liquid droplets having a volume median diameter of 10 μ m to 16 μ m; and

the step of causing the treatment liquid droplets generated in the droplet generating step to impinge on a surface of a substrate being treated;

wherein the droplet generating step includes the step of using ~~generating the droplets of the treatment liquid by using~~ a bifluid nozzle having:

a casing defining an end of the bifluid nozzle;

a liquid outlet port for discharging a treatment liquid; and

a gas outlet port for discharging a gas, an opening including the gas outlet port being formed in the casing at said one end of the bifluid nozzle;

wherein the bifluid nozzle introduces the treatment liquid and the gas into the casing, generates the droplets of the treatment liquid outside the casing, by spraying the gas discharged from the gas outlet port over the treatment liquid discharged from the liquid outlet port, and spouts the droplets onto the surface of the substrate;

the treatment liquid discharged from the liquid outlet port being sprayed by the gas discharged from the gas outlet port to generate the droplets in an open space between the substrate being treated and the end of the bifluid nozzle defined by the casing.

Claim 2 (Canceled)**Claim 3 (Previously Presented)**

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A substrate treatment method as set forth in claim 1, wherein the gas is supplied at a flow rate of 58 liters/min to 78 liters/min for collision with the treatment liquid in the droplet generating step.

Claim 4 (Original)

A substrate treatment method as set forth in claim 3, wherein the treatment liquid is supplied at a flow rate of about 100 ml/min for collision with the gas in the droplet generating step.

Claims 5-24 (Canceled)

Claim 25 (Previously Presented)

A substrate treatment method as set forth in claim 1, wherein the treatment liquid is deionized water, and wherein the gas mixed with the treatment liquid is nitrogen gas.